

Serial No. 10/091,497

AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph beginning on pg. 1, line 4 as follows.

The present application is a division of Application Serial No. 09/525,514, filed on ~~March 6, 2002~~ March 15, 2000, entitled SEMICONDUCTOR DEVICE AND METHOD FOR PRODUCING THE SAME BY DICING, which is based on and claims the benefit of Japanese Patent Application No. 11-76566 filed on March 19, 1999, and No. 11-196345 filed on July 9, 1999, the contents of which are incorporated herein by reference.

Please amend the paragraph beginning on page 2, line 4 as follows.

Further, in the conventional method, the protective sheet needs to be removed from the chips after the dicing-cut step is carried out. If the protective sheet is bonded to the semiconductor wafer firmly, the removal of the protective sheet is difficult and may cause ~~damages~~ damage to the chips ~~by a~~ due to the resulting stress. Therefore, the protective sheet is bonded to the semiconductor wafer ~~at~~ with a relatively small amount of adhesion. Because of this, the protective sheet is easily separated from the semiconductor wafer during the dicing-cut step. As a result, the protective layer cannot protect the movable portions sufficiently.

Please amend the paragraph beginning on page 18, line 26 as follows.

Next, the adhesive film 42 is bonded to the back surface of the semiconductor wafer 11. At the wafer bonding step in the present embodiment, protective members 73 formed by dividing the protective sheet 1 are bonded to the front surface of the semiconductor wafer 11 to expose the bumps 70 from the opening portions 72 while being fixed to the jig 4. As a result, the ~~state~~ state shown in FIG. 13B is provided.